Part Number Customer						
Category	Parameter		Specification	Measurement Method		
OverallWafer	1.0	Diameter	150.00 +/- 0.50 mm			
	2.0	Primary Flat Orientation	{110}+/-1 degree	Wafer Vendor		
	3.0	Primary Flat Length	57.50 +/- 2.50 mm	Wafer Vendor		
	4.0	Overall Thickness	421.00 +/- 10.00 μm	ADE, 100%		
	5.0	LPDs > 0.3um	<30	Tencor Particle counter		
	6.0	Frontsurface condition	Polished, roughness <5A	Guaranteed by process		
	7.0	Total Thickness Variation (TTV)	<5.00µm	Guaranteed by Process		
	8.0	Bow	<60.00µm	ADE to ASTM F534, 100%		
	9.0	Warp	<60.00µm			
	10.0	Edge Chips	0	Bright Light, 100%		
	11.0	Edge Exclusion	5mm			
	12.0	Lasermarking	On wafer BACKSIDE	Guaranteed by process		
HandleSilicon	13.0	Handle Growth Method	CZ	Wafer Vendor		
	14.0	Handle Orientation	{100} +/- 1 degree	Wafer Vendor		
	15.0	Handle Thickness	400.00 +/- 9.00 μm	ADE, 100%		
	16.0	Handle Doping Type	Р	Wafer Vendor		
	17.0	Handle Dopant	Boron	Wafer Vendor		
	18.0	Handle Resistivity	8 ~ 12 Ohmcm	Wafer Vendor		
	19.0	Backside Finish	Polished with lasermark and oxide	Wafer Vendor		
BuriedOxide	20.0	Oxide Type	Thermal			
	21.0	Oxide Thickness	10,000.00 +/- 500.00 A	Nanospec centre point, 4%		
	22.0	Oxide formed on	Handle			
DeviceSilicon	23.0	Device Growth Method	CZ	Wafer Vendor		
	24.0	Device Orientation	{100} +/- 1 degree	Wafer Vendor		
	25.0	Nominal Thickness	20.00 +/- 0.50 µm	Filmetrics, 100% 9-Pt (note3)		
	26.0	Distance to device silicon edge from wafer edge	<= 2mm	Typical by Process		
	27.0	Device Doping Type	N	Wafer Vendor		
	28.0	Device Dopant	Phosphorous	Wafer Vendor		
	29.0	Device Resistivity	3 ~ 5 ohm-cm	Wafer Vendor		
	30.0	Voids	none	IR Inspection, 100%		
	31.0	Scratches	0	Bright Light, 100% (note 2)		
	32.0	Haze	none	Bright Light, 100% (note 2)		
	33.0	Front Surface	Polished, roughness <5A.	Guaranteed by process		

Icemos Technology Ltd

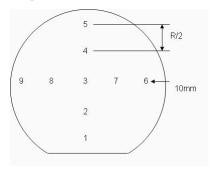
Product Specification

1000.564202

Part Number		Customer		
Category	Parameter	Specification	Measurement Method	
Shipping Details	Wafer per box :	Max 25		
	Packaging :	Taped Polypropylene Wafer Box Empak, Ultrapak, 150.00mm Antistatic Double Bagging		
	Lot Shipment Data	Device Thickness Bow / Warp Data Handle and SOI Thickness		
Explanatory Notes	1. Microscope inspect	tion performed using microscope scan as below. 5x objective.		

2. All bright light inspections performed exclude all wafer area outside the edge exclusion defined in Overall Wafer, Edge Exclusion. High intensity bright lamp inspection as per ASTM F523.

3. 9 point measurement are as shown in the diagram below:



Additional Information